

NOTE:

1. MATERIAL:

- 1.1 INSULATOR: LCP+30%GF, UL94 V-0.
1.2 CONTACT: C5191.
1.3 SHELL: SUS304 3/4H

2. PLATING:

- 2.1 CONTACT:
CONTACT AREA: GOLD PLATING.
SOLDER AREA: 100u" Min MATTE TIN PLATING.
UNDER PLATE: 50u" Min NICKEL PLATING.

2.2 SHELL: 50u" Min. NICKEL PLATED OVERALL

3. CHARACTERISTICS:

- 3.1 ELECTRICAL CHARACTERISTICS:
CONTACT RESISTANCE: 30mΩ MAXIMUM
CONTACT CURRENT RATING: 3A
DIELECTRIC WITHSTANDING VOLTAGE: 500 V R. M. S.
INSULATION RESISTANCE: 1000 MEGOHMS MIN
OPERATING TEMPERATURE: -25~C ~ +85° C

3.2 MECHANICAL:

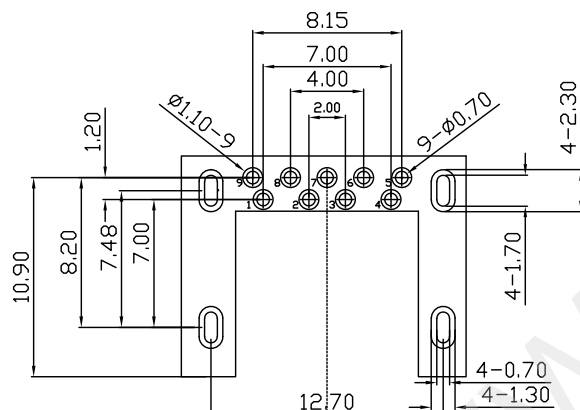
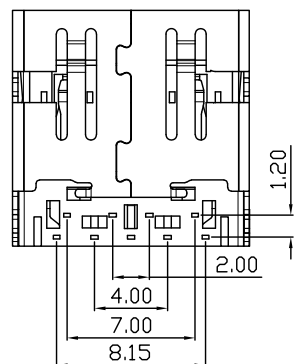
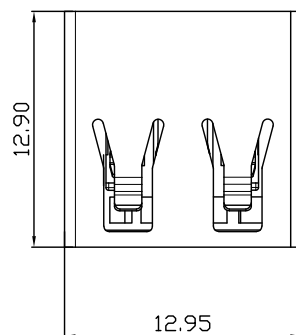
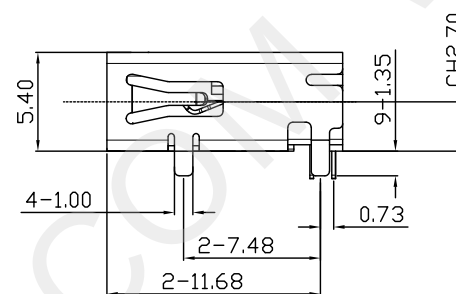
Before lifespan: insertion force 8-25N;
pull-out force 10-25N.

After lifespan: 6N Min.

4. PART MUST COMPLY ROHS SPECIFICATION

5. SOLDER RESISTANCE TEMPERATURE:

260 ± 5° C FOR 3 MINUTES.



Rcommended PCB Layout THK=1.2mm

TOLERANCE=±0.05

X(颜色)

黑/black (B)

蓝/blue (BL)

3	SHELL	SUS304-3/4H	50u" Min. NICKEL PLATED OVERALL
2	CONTACT	C5191	Overall nickel plating 50u" ~ 100u", contact area gold plating 10u", welding leg tin plating 100u"
1	HSG	LCP+30%GF	UL94V-0
NO.	PART NAME	MATERIAL	DESCRIPTION



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TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2" X.X' ±0.5'	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: USB 3.0 AF 板上DIP H=5.4 CH2.7 无卷边	
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC182-USBA09-540-X	MOLD NO.
UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO: HYC-2608271202	SHEET NO. 1 OF 1